

What is claimed is:

1. A micro leadframe package comprising:  
a semiconductor chip;  
a micro leadframe (MLF) having a die pad on which the semiconductor chip is  
5 mounted via adhesive means, leads formed along the outer sides of the die pad, and  
tie bars for supporting four corners of the die pad wherein the die pad, the leads, and  
the tie bars have an oblique etching portion;  
wires for connecting the semiconductor chip with the leads of the MLF; and  
an epoxy molding compound (EMC) for encapsulating the semiconductor chip,  
10 the MLF, and the wires.
2. The micro leadframe package of claim 1, wherein a dimple is formed  
on the die pad of the MLF for increasing the attachment strength between the micro  
leadframe package and the EMC.
- 15 3. The micro leadframe package of claim 2, wherein the plurality of  
dimples are formed along four edges of the die pad.
4. The micro leadframe package of claim 1, wherein dimples are formed  
20 on the leads of the MLF for increasing the attachment strength between the micro  
leadframe package and the EMC.
5. The micro leadframe package of claim 1, wherein dimples are formed  
on the tie bars of the MLF for increasing the attachment strength between the micro  
25 leadframe package and the EMC.
6. The micro leadframe package of claim 1, wherein holes for firm solder  
connection are formed at the tips of the leads which are encapsulated by the EMC.
- 30 7. The micro leadframe package of claim 6, wherein the diameter of the  
holes for firm solder connection ranges from 50% to 95% of the width of the leads.

8. The micro leadframe package of claim 1, wherein the size of the oblique etching portion in a bottom surface of the MLF is greater than that of an upper surface.

5 9. The micro leadframe package of claim 8, wherein the size of the oblique etching portion in the bottom surface of the MLF is greater than that of the upper surface by about 1 – 10%.

10 10. The micro leadframe package of claim 1, wherein the die pad, the leads, and the tie bars are coplanar after being encapsulated by the EMC, and are exposed outward.

15 11. The micro leadframe package of claim 1, wherein an etching solution and an etching method used on the upper surface of the MLF are the same as those used on the bottom surface.